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Product Change Notification - KSRA-04FJDK272 [\(Printer Friendly\)](#)

Date:

09 May 2017

Product Category:

8-bit PIC Microcontrollers

Notification subject:

CCB 2937 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L QFN-S package at NSEB assembly

Notification text:

PCN Status:

Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L QFN-S package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8600 die attach and G700LTD mold compound material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

| | Pre Change | Post Change |
|----------------------------|--------------------|--------------------|
| Assembly Site | NSEB Assembly Site | NSEB Assembly Site |
| Wire material | Au Wire | CuPdAu Wire |
| Die attach material | 8600 | 8600 |

| | | |
|----------------------------------|---------|---------|
| Molding compound material | G700LTD | G700LTD |
| Lead frame material | C194 | C194 |

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

October 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

| Workweek | May 2017 | | | | | --> | October 2017 | | | | |
|--------------------------|----------|----|----|----|----|-----|--------------|----|----|----|----|
| | 18 | 19 | 20 | 21 | 22 | | 40 | 41 | 42 | 43 | 44 |
| Initial PCN Issue Date | | X | | | | | | | | | |
| Qual Report Availability | | | | | | | | | X | | |
| Final PCN Issue Date | | | | | | | | | X | | |

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

May 09, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-04FJDK272_Affected CPN.pdf](#)

[PCN_KSRA-04FJDK272_Qual Plan.pdf](#)

[PCN_KSRA-04FJDK272_Affected CPN.xlsx](#)

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